LF353

LF353 Wide Bandwidth Dual JFET Input Operational Amplifier



Literature Number: SNOSBH3D

10 mV



LF353

Wide Bandwidth Dual JFET Input Operational Amplifier

General Description

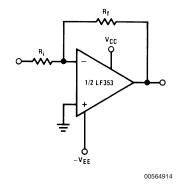
These devices are low cost, high speed, dual JFET input operational amplifiers with an internally trimmed input offset voltage (BI-FET II™ technology). They require low supply current yet maintain a large gain bandwidth product and fast slew rate. In addition, well matched high voltage JFET input devices provide very low input bias and offset currents. The LF353 is pin compatible with the standard LM1558 allowing designers to immediately upgrade the overall performance of existing LM1558 and LM358 designs.

These amplifiers may be used in applications such as high speed integrators, fast D/A converters, sample and hold circuits and many other circuits requiring low input offset voltage, low input bias current, high input impedance, high slew rate and wide bandwidth. The devices also exhibit low noise and offset voltage drift.

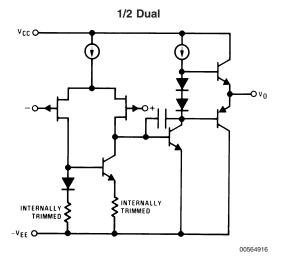
Features

Low input bias current:	50pA
Low input noise voltage:	25 nV/√Hz
Low input noise current:	0.01 pA/√Hz
■ Wide gain bandwidth:	4 MHz
■ High slew rate:	13 V/µs
■ Low supply current:	3.6 mA
High input impedance:	$10^{12}\Omega$
Low total harmonic distortion :	≤0.02%
■ Low 1/f noise corner:	50 Hz
■ Fast settling time to 0.01%:	2 µs

Typical Connection



Simplified Schematic



BI-FET II™ is a trademark of National Semiconductor Corporation

Connection Diagram

■ Internally trimmed offset voltage:

Top View
Order Number LF353M, LF353MX or LF353N
See NS Package Number M08A or N08E

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage ±18V Power Dissipation (Note 2) Operating Temperature Range 0°C to +70°C $T_i(MAX)$ 150°C ±30V Differential Input Voltage Input Voltage Range (Note 3) ±15V **Output Short Circuit Duration** Continuous Storage Temperature Range -65°C to +150°C Lead Temp. (Soldering, 10 sec.) 260°C

Soldering Information
Dual-In-Line Package

Soldering (10 sec.) 260°C

Small Outline Package

Vapor Phase (60 sec.) Infrared (15 sec.) 215°C

220°C

See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.

 $\begin{array}{ll} \text{ESD Tolerance (Note 8)} & \text{1000V} \\ \theta_{\text{JA}} \text{ M Package} & \text{TBD} \end{array}$

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

DC Electrical Characteristics

(Note 5)

Symbol	Parameter	Conditions		LF353		Units
			MIn	Тур	Max	
V _{os}	Input Offset Voltage	$R_S=10k\Omega$, $T_A=25^{\circ}C$		5	10	mV
		Over Temperature			13	mV
$\Delta V_{OS}/\Delta T$	Average TC of Input Offset Voltage	R _S =10 kΩ		10		μV/°C
I _{os}	Input Offset Current	T _j =25°C, (Notes 5, 6)		25	100	pA
		T _j ≤70°C			4	nA
I _B	Input Bias Current	T _j =25°C, (Notes 5, 6)		50	200	pA
		T _j ≤70°C			8	nA
R _{IN}	Input Resistance	T _j =25°C		10 ¹²		Ω
A _{VOL}	Large Signal Voltage Gain	V _S =±15V, T _A =25°C	25	100		V/mV
		$V_O=\pm 10V$, $R_L=2 k\Omega$				
		Over Temperature	15			V/mV
V _O	Output Voltage Swing	$V_S=\pm 15V$, $R_L=10k\Omega$	±12	±13.5		V
V _{CM}	Input Common-Mode Voltage	V _S =±15V	±11	+15		V
	Range			-12		V
CMRR	Common-Mode Rejection Ratio	R _S ≤ 10kΩ	70	100		dB
PSRR	Supply Voltage Rejection Ratio	(Note 7)	70	100		dB
I _S	Supply Current			3.6	6.5	mA

AC Electrical Characteristics

(Note 5)

Symbol	Parameter	Conditions	LF353			Units
			Min	Тур	Max	
	Amplifier to Amplifier Coupling	T _A =25°C, f=1 Hz-20 kHz		-120		dB
		(Input Referred)				
SR	Slew Rate	V _S =±15V, T _A =25°C	8.0	13		V/µs
GBW	Gain Bandwidth Product	V _S =±15V, T _A =25°C	2.7	4		MHz
e _n	Equivalent Input Noise Voltage	$T_A=25$ °C, $R_S=100\Omega$,		16		nV/√Hz
		f=1000 Hz				11077172
i _n	Equivalent Input Noise Current	T _j =25°C, f=1000 Hz		0.01		pA/√Hz

AC Electrical Characteristics (Continued)

(Note 5)

Symbol	Parameter	Conditions	LF353			Units
			Min	Тур	Max	
THD	Total Harmonic Distortion	A _V =+10, RL=10k,		<0.02		%
		V _O =20Vp-p,				
		BW=20 Hz-20 kHz				

Note 2: For operating at elevated temperatures, the device must be derated based on a thermal resistance of 115°C/W typ junction to ambient for the N package, and 158°C/W typ junction to ambient for the H package.

Note 3: Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.

Note 4: The power dissipation limit, however, cannot be exceeded.

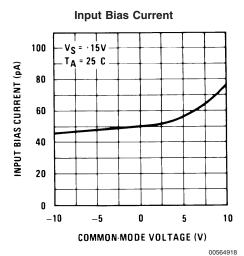
Note 5: These specifications apply for $V_S=\pm15V$ and $0^{\circ}C \le T_A \le +70^{\circ}C$. V_{OS} , I_B and I_{OS} are measured at $V_{CM}=0$.

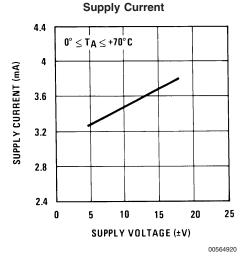
Note 6: The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T_j . Due to the limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, P_D . $T_j = T_A + \theta_{jA}$ P_D where θ_{jA} is the thermal resistance from junction to ambient. Use of a heat sink is recommended if input bias current is to be kept to a minimum.

Note 7: Supply voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously in accordance with common practice. $V_S = \pm 6V$ to $\pm 15V$.

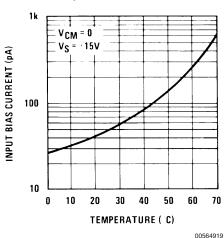
Note 8: Human body model, 1.5 k Ω in series with 100 pF.

Typical Performance Characteristics

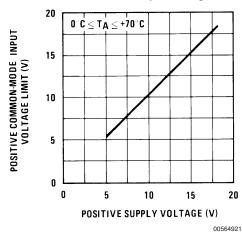




Input Bias Current



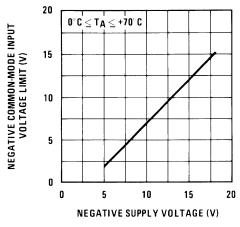
Positive Common-Mode Input Voltage Limit



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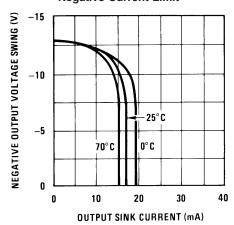
Typical Performance Characteristics (Continued)

Negative Common-Mode Input Voltage Limit



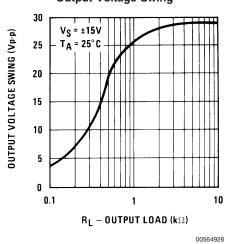
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Negative Current Limit

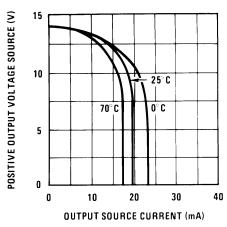


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Output Voltage Swing

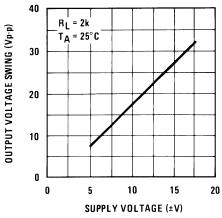


Positive Current Limit



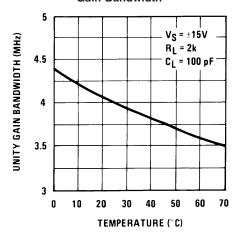
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Voltage Swing



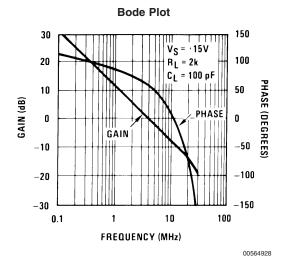
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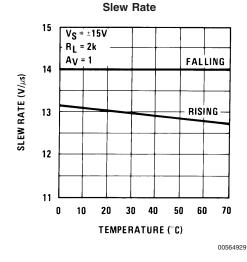
Gain Bandwidth



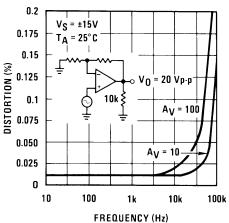
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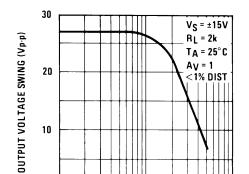
Typical Performance Characteristics (Continued)





Distortion vs. Frequency





Undistorted Output Voltage Swing

0056493

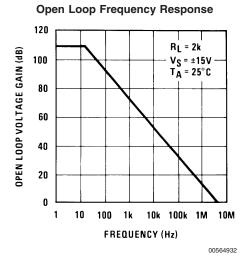
Common-Mode Rejection Ratio

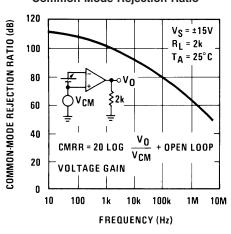
100k

FREQUENCY (Hz)

0

10k



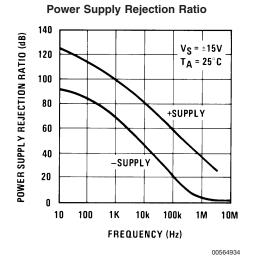


00564933

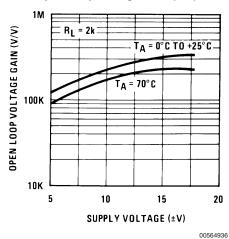
1M

00564931

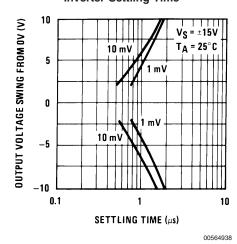
Typical Performance Characteristics (Continued)



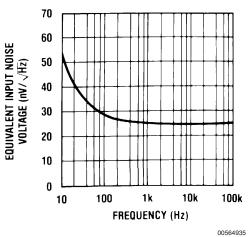




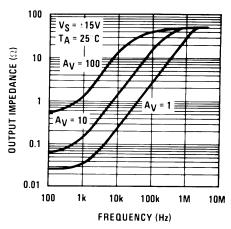
Inverter Settling Time



Equivalent Input Noise Voltage



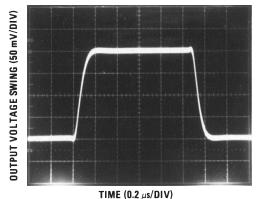
Output Impedance



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Pulse Response

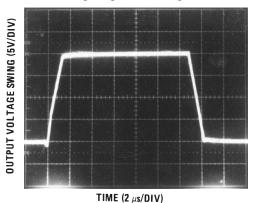
Small Signaling Inverting



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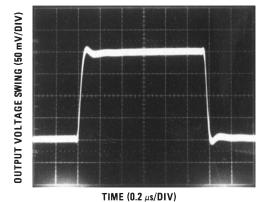
0056490

Large Signal Inverting



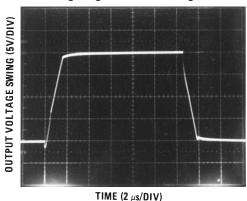
00564906

Small Signal Non-Inverting



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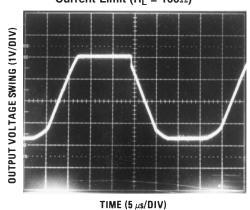
Large Signal Non-Inverting



00564907

00564905

Current Limit ($R_L = 100\Omega$)



00564908

Application Hints

These devices are op amps with an internally trimmed input offset voltage and JFET input devices (BI-FET II). These JFETs have large reverse breakdown voltages from gate to source and drain eliminating the need for clamps across the inputs. Therefore, large differential input voltages can easily be accommodated without a large increase in input current. The maximum differential input voltage is independent of the

supply voltages. However, neither of the input voltages should be allowed to exceed the negative supply as this will cause large currents to flow which can result in a destroyed unit.

Exceeding the negative common-mode limit on either input will force the output to a high state, potentially causing a reversal of phase to the output. Exceeding the negative common-mode limit on both inputs will force the amplifier output to a high state. In neither case does a latch occur

Application Hints (Continued)

since raising the input back within the common-mode range again puts the input stage and thus the amplifier in a normal operating mode.

Exceeding the positive common-mode limit on a single input will not change the phase of the output; however, if both inputs exceed the limit, the output of the amplifier will be forced to a high state.

The amplifiers will operate with a common-mode input voltage equal to the positive supply; however, the gain bandwidth and slew rate may be decreased in this condition. When the negative common-mode voltage swings to within 3V of the negative supply, an increase in input offset voltage may occur.

Each amplifier is individually biased by a zener reference which allows normal circuit operation on $\pm 6V$ power supplies. Supply voltages less than these may result in lower gain bandwidth and slew rate.

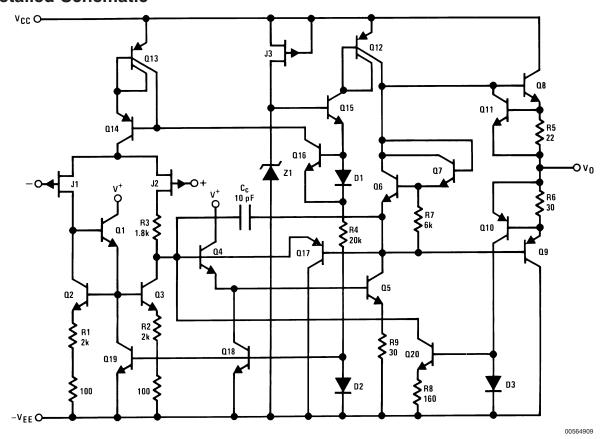
The amplifiers will drive a 2 k Ω load resistance to $\pm 10V$ over the full temperature range of 0°C to +70°C. If the amplifier is forced to drive heavier load currents, however, an increase in input offset voltage may occur on the negative voltage swing and finally reach an active current limit on both positive and negative swings.

Precautions should be taken to ensure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pick-up" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground.

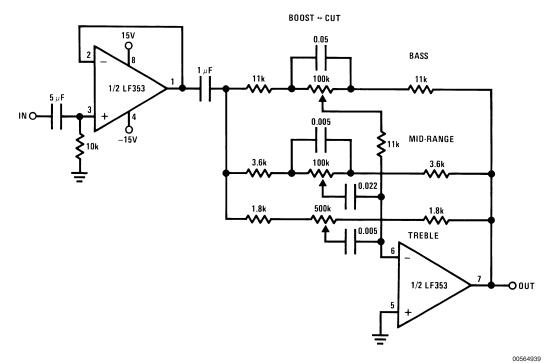
A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to AC ground set the frequency of the pole. In many instances the frequency of this pole is much greater than the expected 3 dB frequency of the closed loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately 6 times the expected 3 dB frequency a lead capacitor should be placed from the output to the input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than or equal to the original feedback pole time constant.

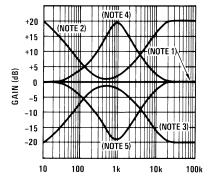
Detailed Schematic



Typical Applications

Three-Band Active Tone Control





FREQUENCY (Hz)

00564940

Note 1: All controls flat.

Note 2: Bass and treble boost, mid flat.

Note 3: Bass and treble cut, mid flat.

Note 4: Mid boost, bass and treble flat.

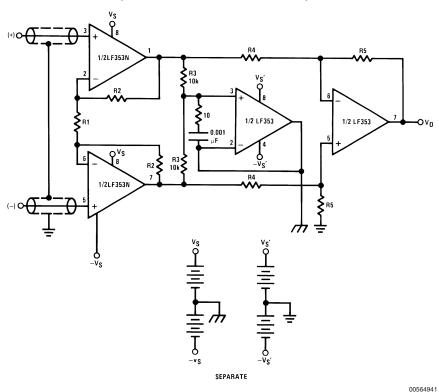
Note 5: Mid cut, bass and treble flat.

• All potentiometers are linear taper

• Use the LF347 Quad for stereo applications

Typical Applications (Continued)

Improved CMRR Instrumentation Amplifier

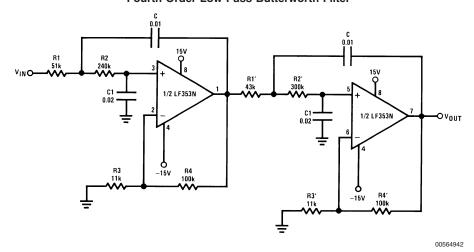


$$A_V = \left(\frac{2R2}{R1} + 1\right) \quad \frac{R5}{R4}$$

 $\uparrow \uparrow \uparrow$ and $\frac{1}{-}$ are separate isolated grounds Matching of R2's, R4's and R5's control CMRR With A $_{VT}$ = 1400, resistor matching = 0.01%: CMRR = 136 dB

- Very high input impedance
- Super high CMRR

Fourth Order Low Pass Butterworth Filter

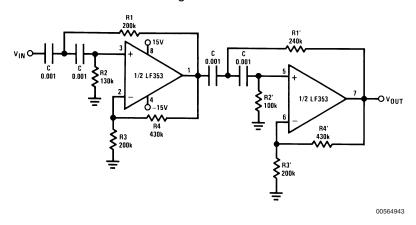


Typical Applications (Continued)

• Corner frequency (f_C) =
$$\sqrt{\frac{1}{R1R2CC1}}$$
 • $\frac{1}{2\pi}$ = $\sqrt{\frac{1}{R1'R2'CC1}}$ • $\frac{1}{2\pi}$

- Passband gain $(H_0) = (1 + R4/R3) (1 + R4'/R3')$
- First stage Q = 1.31
- Second stage Q = 0.541
- Circuit shown uses nearest 5% tolerance resistor values for a filter with a corner frequency of 100 Hz and a passband gain of 100
- Offset nulling necessary for accurate DC performance

Fourth Order High Pass Butterworth Filter

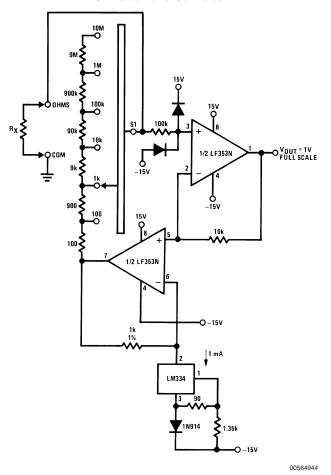


• Corner frequency (f_c) =
$$\sqrt{\frac{1}{R1R2C^2}}$$
 • $\frac{1}{2\pi}$ = $\sqrt{\frac{1}{R1'R2'C^2}}$ • $\frac{1}{2\pi}$

- Passband gain $(H_0) = (1 + R4/R3) (1 + R4'/R3')$
- First stage Q = 1.31
- \bullet Second stage Q = 0.541
- Circuit shown uses closest 5% tolerance resistor values for a filter with a corner frequency of 1 kHz and a passband gain of 10.

Typical Applications (Continued)

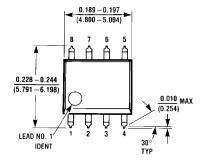
Ohms to Volts Converter

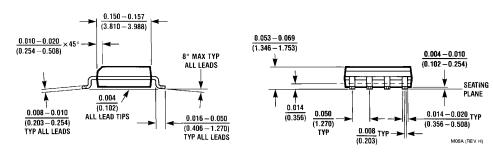


$$V_O = \frac{1V}{R_{LADDER}} \times R_X$$

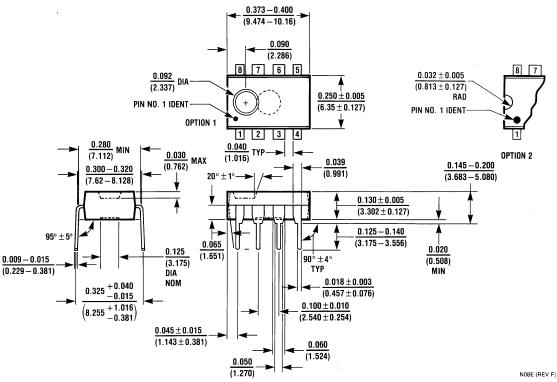
Where $R_{\mbox{\scriptsize LADDER}}$ is the resistance from switch S1 pole to pin 7 of the LF353.

Physical Dimensions inches (millimeters) unless otherwise noted





Order Number LF353M or LF353MX NS Package Number M08A



Molded Dual-In-Line Package Order Number LF353N NS Package N08E

Notes

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